

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. . . . . 09/360,292  
Filing Date . . . . . July 22, 1999  
Inventor . . . . . Sujit Sharan et al.  
Assignee . . . . . Micron Technology, Inc.  
Group Art Unit . . . . . 1746  
Examiner . . . . . S. Ahmed  
Attorney's Docket No. . . . . MI22-1106  
Title: Plasma Etching Process (as Amended)



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RESPONSE TO SEPTEMBER 25, 2001 OFFICE ACTION

To: Box Non-Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)  
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Sir:

Responsive to the Office Action dated September 25, 2001, Applicant amends and remarks as follows:

AMENDMENTS

In the Title:

Please replace the title with the following: --PLASMA ETCHING PROCESS--.

In the Claims:

Please cancel claims 1-14, 25-34 and 42-60 without prejudice.

### REMARKS

The Examiner has required restriction under 35 U.S.C. § 121 between claims 1-14 and 25-34 (Group I - drawn to a process for etching a carbon containing material), claims 15-24 and 35-41 (Group II - drawn to an etching process), claims 42-53 (Group III - drawn to an etching/deposition process), and claims 54-60 (Group IV - drawn to a process of forming a conductive contact). Applicant hereby elects without traverse claims 15-24 and 35-41 (Group II) for prosecution on the merits. Accordingly, claims 1-14, 25-34 and 42-60 (Groups I, III and IV) have been canceled without prejudice.

Respectfully submitted,

Dated: 10-19-01

By:   
Mark S. Matkin  
Reg. No. 32,268